

In the Specification:

Please amend the specification as follows:

The paragraph at page 5, line 20 to page 6, line 18:

"Further, by the other words, the present invention is to obtain the epoxy resin having a certain molecular weight distribution containing components of various degree of polymerization n. More specifically, the epoxy resin of the present invention is the polymer epoxy resin of higher epoxy equivalent than 250g/eq, of higher average molecular weight than 500, in the case of baking coating of higher average molecular weight than ~~1000~~ 10,000, further the present invention is the polyhydroxy polyether resin having a self film forming ability and having a structural unit of the present invention. In the epoxy resin of the present invention, the semi-solid epoxy resin of epoxy equivalent 250g/eq contains the epoxy resin whose content of n=0 component is 50%, forms homogeneous vanish state when dissolved in aromatic hydro carbon (for example toluene) and n=0 component is separated from the solvent and can maintain the form of coating stable without crystallization. Further, in the case of middle molecular weight epoxy resin of epoxy equivalent 800g/eq, which is applied as the powder coating, n=0 component is 7.5% and the cured coated film thereof can be the coated film with good heat resistance, boiled water resistance, flexibility and adhesion. Furthermore, the cured coated film which applies the epoxy resin of high molecular weight of epoxy equivalent

2100g/eq and polyhydroxypolyether resin of epoxy equivalent 35000g/eq can provide the coated film with good heat resistance and retort blushing resistance. Still further, polyhydroxypolyether resin of epoxy equivalent 35000g/eq can accomplish the self film forming ability by resin alone. When the epoxy resin based on the present invention is compared with the ordinary used bisphenol A epoxy resins, heat resistance and water resistance are remarkably improved. And when the middle molecular weight epoxy resin whose epoxy equivalent is from 800 to 2000g/eq of the present invention which is used for powder coating with the crystalline epoxy resin (epoxy equivalent is 189g/eq) of low epoxy equivalent, flexibility and adhesion are remarkably improved, and is an important effect of the present invention. Consequently, the industrial applicability of the present invention is remarkably expanded, and is fully satisfying the practical efficiency. In the present invention, the application to a coating is shown as the example, however, the epoxy resin of the present invention can be applied to any uses which can use the efficiency of said epoxy resin."